

AMENDMENTS TO THE ABSTRACT

Please replace the paragraph on page 46 with the following rewritten paragraph:

-- ~~Disclosed herein is a~~A semiconductor wafer protection structure including a semiconductor wafer and a protective sheet overlaid on a circuit surface of the semiconductor wafer, wherein the protective sheet has a larger diameter than the outer diameter of the semiconductor wafer. ~~The invention provides semiconductor~~Semiconductor wafer protection structures and methods, and laminated protective sheet for use therein ~~that are~~ provided and enable prevention of damage to a wafer during grinding and transportation when the wafer is ground to an ultrathin thickness and transported. Also provided is a process for processing a semiconductor wafer whereby damage to the wafer can be reduced during application and cutting of an adhesive sheet. --